

Sheet 1 of 1

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

ATTY. DKT. NO.

SERIAL NO.

219.40779X00

INFORMATION DISCLOSURE STATEMENT  
BY APPLICANT

(Use several sheets if necessary)

APPLICANT

B. CHANDRAN ET AL.

FILING DATE

GROUP

December 21, 2001

2827

## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
JSV	AA 5,369,551	11/29/94	Gore et al.			11/08/93
	AB 5,872,401	02/16/99	Huff et al.			02/29/96
	AC 5,889,652	03/30/99	Turturo			04/21/97
	AD 5,931,371	08/03/99	Pao et al.			01/16/97
	AE 5,936,304	08/10/99	Lii et al.			12/10/97
JSV	AF 6,049,124	04/11/00	Raiser et al.			12/10/97
	AG					
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	AI					
	AJ					
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	AL					

## FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation/Abstract	
						Yes	No
	AM						
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## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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Examiner

John B. Viguerie

Date Considered

June 28, 2003

 10/023819  
 12/21/01

Sheet 1 of 1

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## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
BK	AA 5,369,551	11/29/94	Gore et al.	361	767	11/08/93
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Examiner

John B. Vigorlin

Date Considered

April 29, 2003

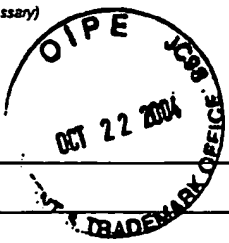
Paper No. 0403a

 10/023819  
 12/21/01

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number 10/023,819  
Filing Date December 21, 2001  
First Named Inventor Chandran, Biju  
Group Art Unit ~~2827~~ 2841  
Examiner Name Vigushin, John

Sheet 1 of 1

Attorney Docket No: 884.A27US1

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Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date if Appropriate
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**FOREIGN PATENT DOCUMENTS**

Examiner Initials *	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>
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**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
<i>[Signature]</i>		HONG, B. Z., "Thermal Fatigue Analysis of CBGA Package with Lead-Free Solder Fillets", <u>Proceedings of the 1998 Intersociety Conference on Thermal Phenomena</u> , (Aug., 1998), 205-211	
<i>[Signature]</i>		KARIM, Z. S., et al., "Lead-Free Bump Interconnections for Flip-Chip Applications", <u>Proceedings of the 2000 IEEE/CPMT International Electronics Manufacturing Technology Symposium</u> , (Jan., 2000), 274-278	
<i>[Signature]</i>		WANG, T., et al., "Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump", <u>Proceedings of the 2001 Electronic Components and Technology Conference</u> , (Apr., 2001), 5 p.	
<i>[Signature]</i>		XIAO, G., et al., "The Effect of Cu Stud Structure and Eutectic Solder Electroplating on Intermetallic Growth and Reliability of Flip-Chip Solder Bump", <u>Proceedings of the 2000 Electronic Components and Technology Conference</u> , (Sep., 2000), 54-59	

*Paper No. 1004*

EXAMINER

*John B. Vigushin*

DATE CONSIDERED

*April 08, 2005*

Substitute Disclosure Statement Form (PTO-1449)

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